

Core material :
Polytherm TC-Lam 1.3

Manufacturer:
MSC Polymer AG

Thickness Dielectric:
100µm

Protective film:
HT (High Temperature ≤280°C)

Material characteristic (1,5mm/100µm/35µm Cu)	Testmethod/-term	Unit	Spec.	Typical Values
Thermal load 288°C, dip test, no Delamination	TM 650-2.4.13.1	sec	≤10	90
Copper adhesion	TM 650-2.4.8 / A 288°C, 10 s	N/mm N/mm		1.85 1.87
Dielectric Strength	TM 650-2.6.2 / A	kV		3
Electric Strength	TM 650 / A	kV/mm		30
Heat conduction Dielectric	A	W/m*K		1.3
Heat resistance Dielectric	SJ20780 / A	K/W	≤1.50	1.20
Surface insulation resistance	TM 650-2.5.17.1 / E24/125 C96/35/90	MΩ MΩ	10 ³ 10 ⁴	10 ⁷ 10 ⁷
Volume resistance	TM 650-2.5.17.1 / E24/125 C96/35/90	MΩ -cm MΩ -cm	6*10 ⁴ 6*10 ⁴	10 ⁵ 10 ⁷
Flammable	UL-94	Klasse	V-0	V-0
Comparative tracking resistance (CTI)	UL746A	V	PLC 0	PLC 0
Water absorption	TM 650-2.6.2.1 / D-24/23	%	≤0.5	0.1
Glass transition temperature (Tg)	A	°C	---	100

Thickness tolerance Dielectric: **IPC-4101B grade B/L**

Source: MSC - POLYMER AG